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AN EXPERIMENTAL STUDY ON EARTHQUAKE FAULT RUPTURE PROPAGATION THROUGH A SANDY SOIL DEPOSIT

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This paper presents the results of experimental studies to examine propagation of fault ruptures with particular concern on dip-slip fault. The pattern of rupture propagation through a sandy soil and the location of surface rupture were investigated. The distortion of surface ground accompanied by fault rupture has been examined as well. The 1-g model tests showed that the location of surface fault rupture varied depending on the model thickness due to strongly dilatant behavior of sand under low confinement. However, the increase of confinement at centrifuge models provided no definite variation of the location against the change of model thickness, which suggested the importance of interpretation about the results from small scale sandbox test.

Key Words: earthquake fault rupture, fault test, centrifuge test, reverse and normal fault

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